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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



NGTB30N120FL2WG

IGBT - Field Stop II

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop II Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co-packaged free wheeling diode with a low forward voltage.

Features

- Extremely Efficient Trench with Field Stop Technology
- $T_{Jmax} = 175^{\circ}C$
- Soft Fast Reverse Recovery Diode
- Optimized for High Speed Switching
- 10 μs Short Circuit Capability
- This is a Pb-Free Device

Typical Applications

- Solar Inverter
- Uninterruptible Power Supplies (UPS)
- Welding

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V_{CES}	1200	V
Collector current @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	I_C	60 30	A
Pulsed collector current, T_{pulse} limited by T_{Jmax} , 10 μs Pulse, $V_{GE} = 15 V$	I_{CM}	120	A
Diode forward current @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	I_F	60 30	A
Diode pulsed current, T_{pulse} limited by T_{Jmax}	I_{FM}	120	A
Gate-emitter voltage Transient gate-emitter voltage ($T_{pulse} = 5 \mu s$, $D < 0.10$)	V_{GE}	± 20 ± 30	V
Power Dissipation @ $T_C = 25^{\circ}C$ @ $T_C = 100^{\circ}C$	P_D	452 227	W
Short Circuit Withstand Time $V_{GE} = 15 V$, $V_{CE} = 500 V$, $T_J \leq 150^{\circ}C$	T_{SC}	10	μs
Operating junction temperature range	T_J	-55 to +175	$^{\circ}C$
Storage temperature range	T_{stg}	-55 to +175	$^{\circ}C$
Lead temperature for soldering, 1/8" from case for 5 seconds	T_{SLD}	260	$^{\circ}C$

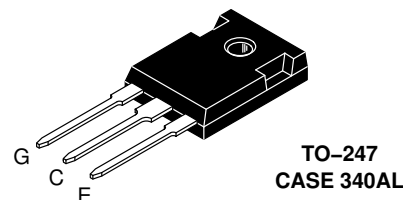
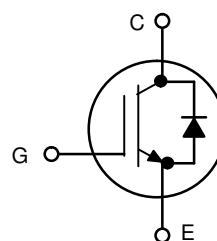
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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30 A, 1200 V
 $V_{CEsat} = 2.0 V$
 $E_{off} = 0.7 mJ$



MARKING DIAGRAM



A = Assembly Location
 Y = Year
 WW = Work Week
 G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB30N120FL2WG	TO-247 (Pb-Free)	30 Units / Rail

NGTB30N120FL2WG

THEMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{\theta JC}$	0.33	$^{\circ}\text{C}/\text{W}$
Thermal resistance junction-to-case, for Diode	$R_{\theta JC}$	0.5	$^{\circ}\text{C}/\text{W}$
Thermal resistance junction-to-ambient	$R_{\theta JA}$	40	$^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
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STATIC CHARACTERISTIC

Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, I_C = 500\ \mu\text{A}$	$V_{(BR)CES}$	1200	-	-	V
Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}, I_C = 30\text{ A}$ $V_{GE} = 15\text{ V}, I_C = 30\text{ A}, T_J = 175^{\circ}\text{C}$	V_{CEsat}	-	2.00	2.30	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_C = 400\ \mu\text{A}$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate-emitter short-circuited	$V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}$ $V_{GE} = 0\text{ V}, V_{CE} = 1200\text{ V}, T_J = 175^{\circ}\text{C}$	I_{CES}	-	-	1.0 2	mA
Gate leakage current, collector-emitter short-circuited	$V_{GE} = 20\text{ V}, V_{CE} = 0\text{ V}$	I_{GES}	-	-	200	nA

Input capacitance	$V_{CE} = 20\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$	C_{ies}	-	5250	-	pF
Output capacitance		C_{oes}	-	170	-	
Reverse transfer capacitance		C_{res}	-	100	-	
Gate charge total	$V_{CE} = 600\text{ V}, I_C = 30\text{ A}, V_{GE} = 15\text{ V}$	Q_g	-	220	-	nC
Gate to emitter charge		Q_{ge}	-	45	-	
Gate to collector charge		Q_{gc}	-	105	-	

SWITCHING CHARACTERISTIC, INDUCTIVE LOAD

Turn-on delay time	$T_J = 25^{\circ}\text{C}$ $V_{CC} = 600\text{ V}, I_C = 30\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 0\text{ V}/15\text{ V}$	$t_{d(on)}$	-	98	-	ns	
Rise time		t_r	-	35	-		
Turn-off delay time		$t_{d(off)}$	-	210	-		
Fall time			t_f	-	130	-	mJ
Turn-on switching loss		E_{on}	-	2.6	-		
Turn-off switching loss		E_{off}	-	0.7	-		
Total switching loss		E_{ts}	-	3.3	-		
Turn-on delay time	$T_J = 175^{\circ}\text{C}$ $V_{CC} = 600\text{ V}, I_C = 30\text{ A}$ $R_g = 10\ \Omega$ $V_{GE} = 0\text{ V}/15\text{ V}$	$t_{d(on)}$	-	92	-	ns	
Rise time		t_r	-	35	-		
Turn-off delay time		$t_{d(off)}$	-	220	-		
Fall time			t_f	-	260	-	mJ
Turn-on switching loss		E_{on}	-	3.5	-		
Turn-off switching loss		E_{off}	-	1.8	-		
Total switching loss		E_{ts}	-	5.3	-		

DIODE CHARACTERISTIC

Forward voltage	$V_{GE} = 0\text{ V}, I_F = 30\text{ A}$ $V_{GE} = 0\text{ V}, I_F = 30\text{ A}, T_J = 175^{\circ}\text{C}$	V_F	-	1.75	-	V
Reverse recovery time	$T_J = 25^{\circ}\text{C}$ $I_F = 30\text{ A}, V_R = 400\text{ V}$ $di_F/dt = 200\text{ A}/\mu\text{s}$	t_{rr}	-	240	-	ns
Reverse recovery charge		Q_{rr}	-	2.5	-	μC
Reverse recovery current		I_{rrm}	-	18	-	A
Reverse recovery time	$T_J = 175^{\circ}\text{C}$ $I_F = 30\text{ A}, V_R = 400\text{ V}$ $di_F/dt = 200\text{ A}/\mu\text{s}$	t_{rr}	-	413	-	ns
Reverse recovery charge		Q_{rr}	-	4.3	-	μC
Reverse recovery current		I_{rrm}	-	20	-	A

NGTB30N120FL2WG

TYPICAL CHARACTERISTICS

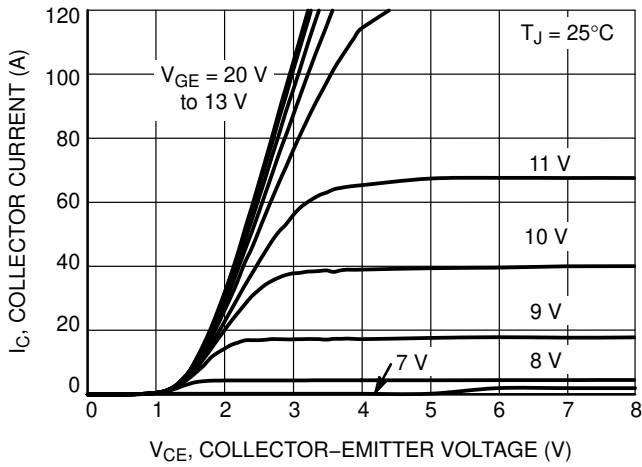


Figure 1. Output Characteristics

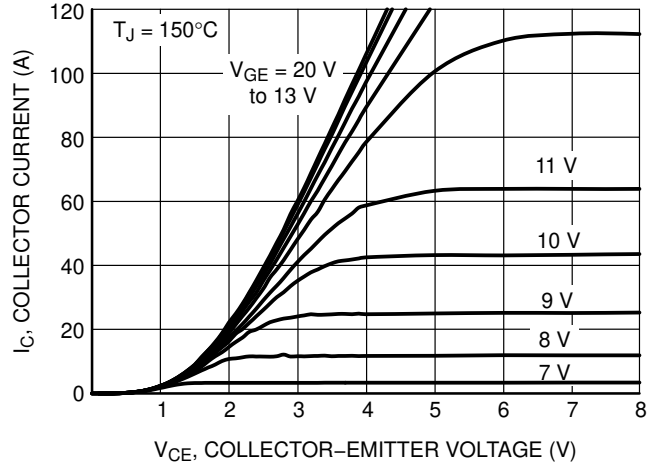


Figure 2. Output Characteristics

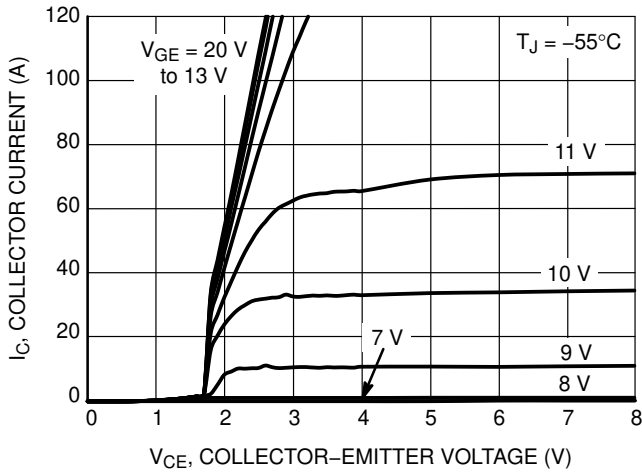


Figure 3. Output Characteristics

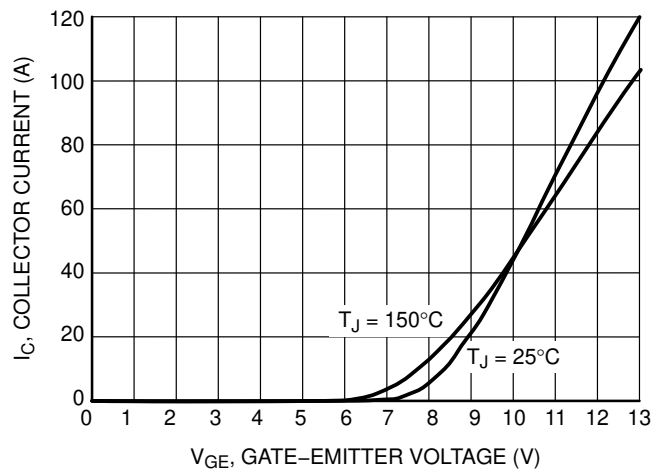


Figure 4. Typical Transfer Characteristics

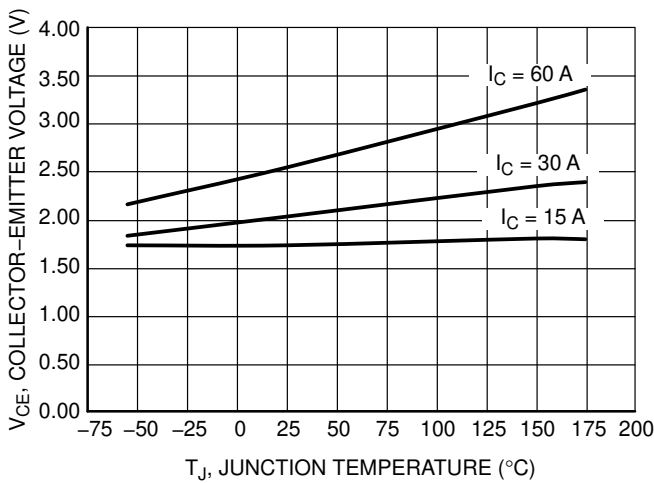


Figure 5. $V_{CE(sat)}$ vs T_J

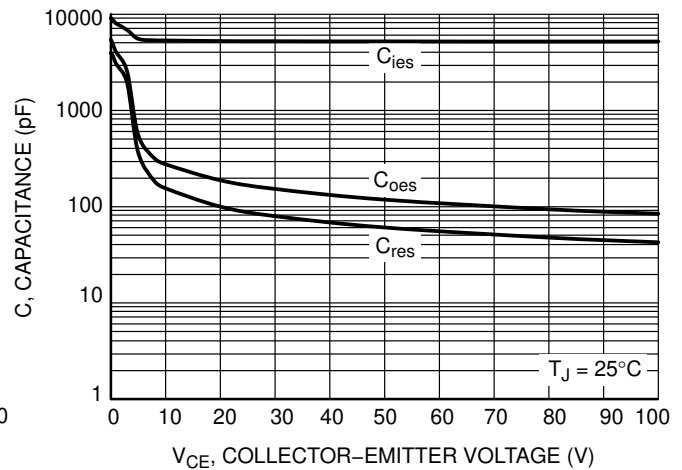


Figure 6. Typical Capacitance

NGTB30N120FL2WG

TYPICAL CHARACTERISTICS

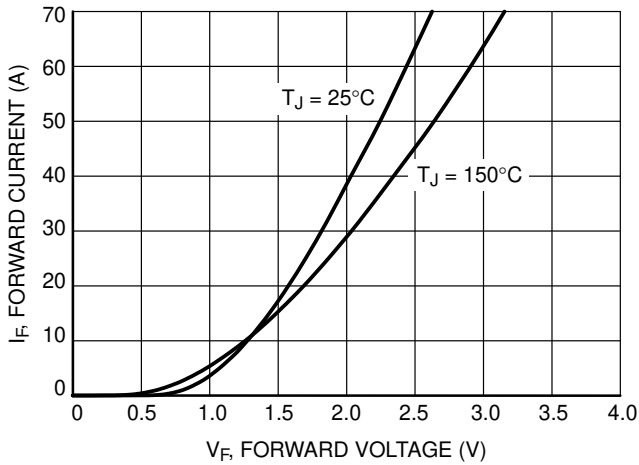


Figure 7. Diode Forward Characteristics

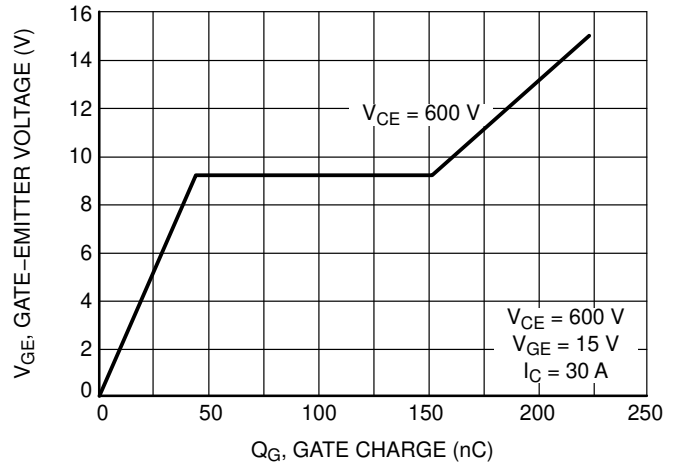


Figure 8. Typical Gate Charge

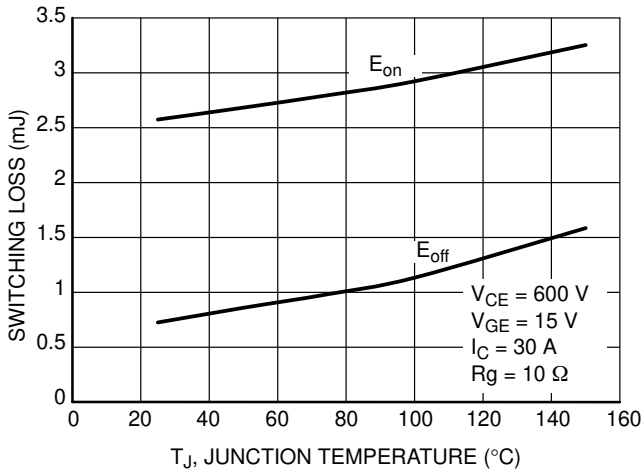


Figure 9. Switching Loss vs. Temperature

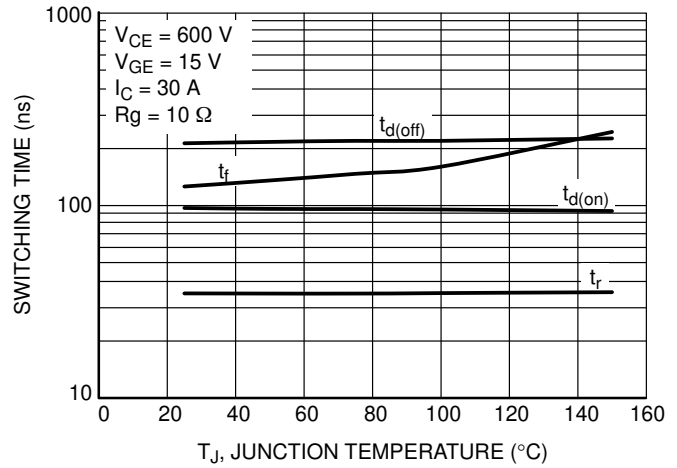


Figure 10. Switching Time vs. Temperature

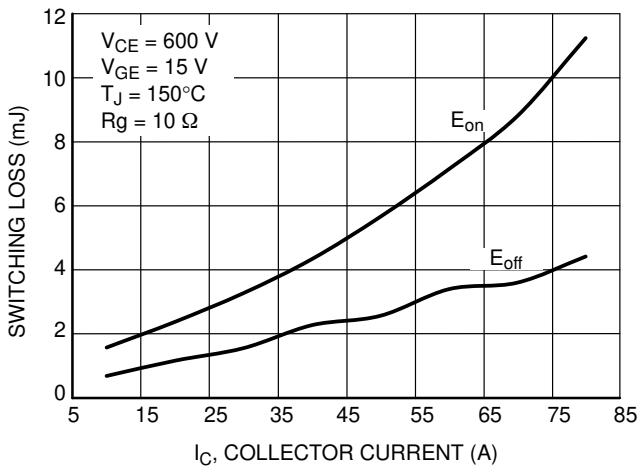


Figure 11. Switching Loss vs. I_C

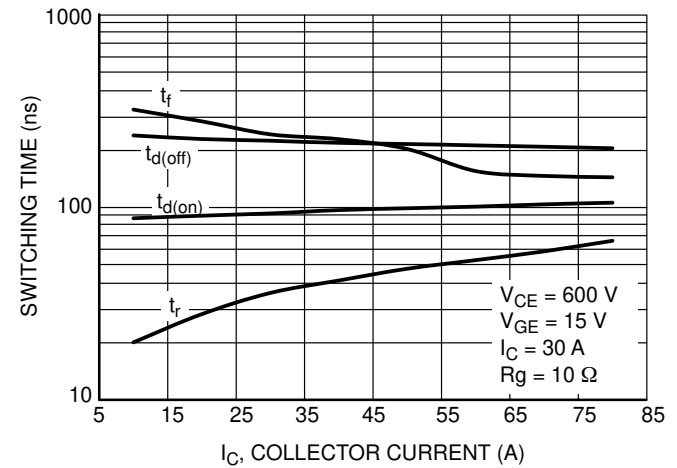


Figure 12. Switching Time vs. I_C

NGTB30N120FL2WG

TYPICAL CHARACTERISTICS

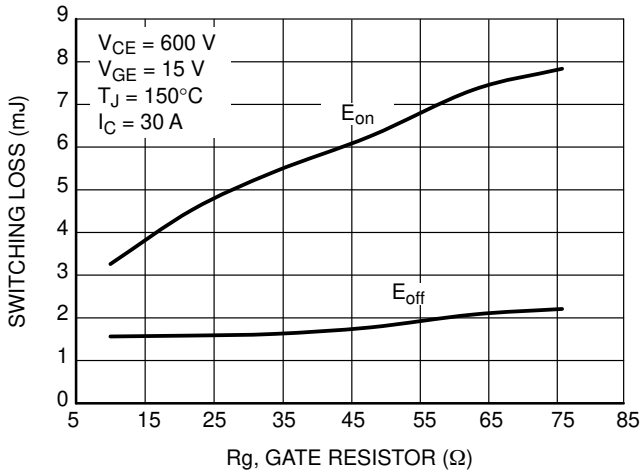


Figure 13. Switching Loss vs. R_g

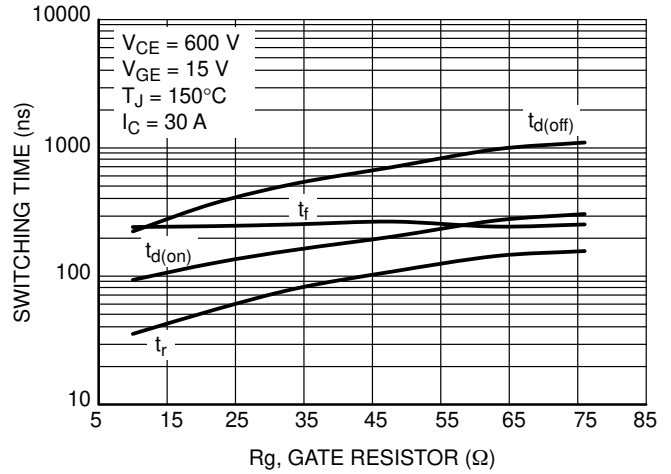


Figure 14. Switching Time vs. R_g

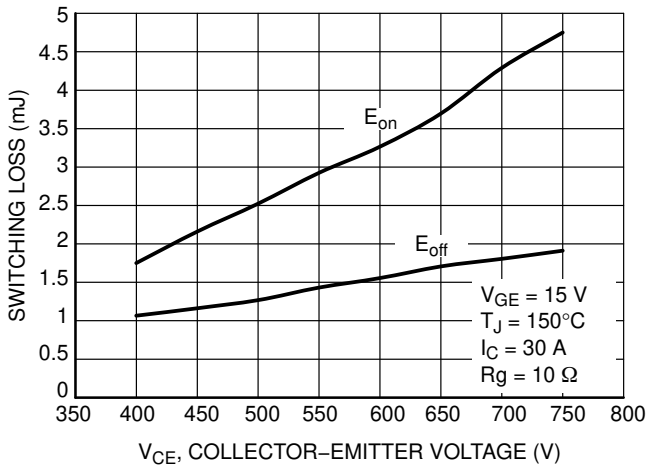


Figure 15. Switching Loss vs. V_{CE}

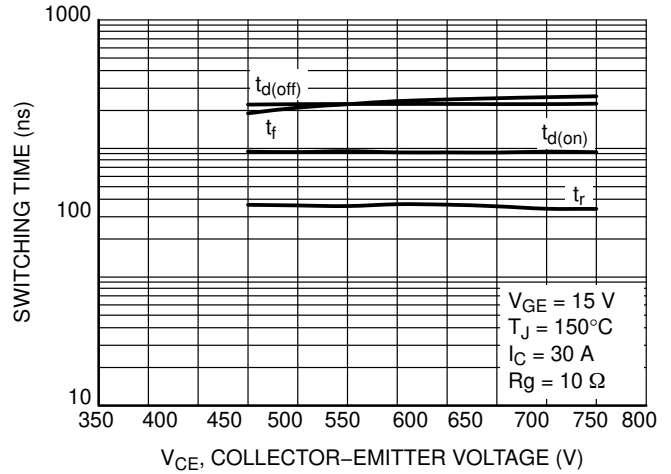


Figure 16. Switching Time vs. V_{CE}

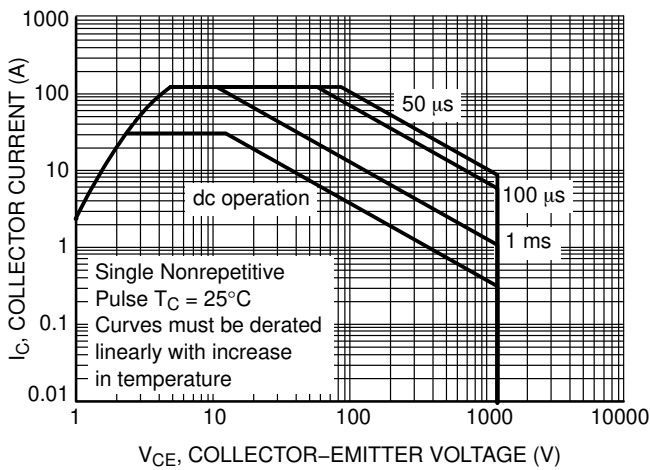


Figure 17. Safe Operating Area

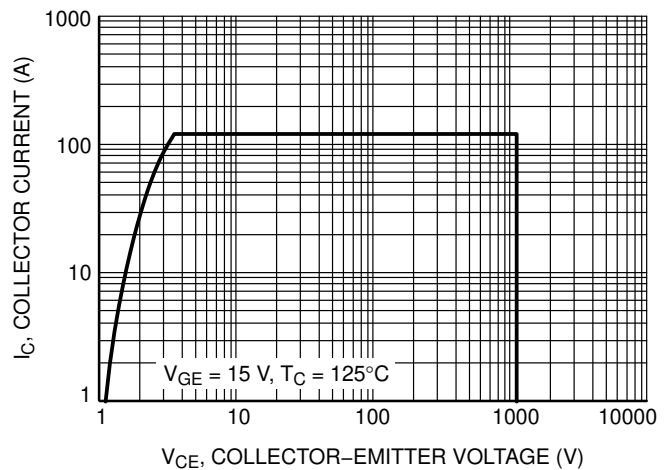


Figure 18. Reverse Bias Safe Operating Area

NGTB30N120FL2WG

TYPICAL CHARACTERISTICS

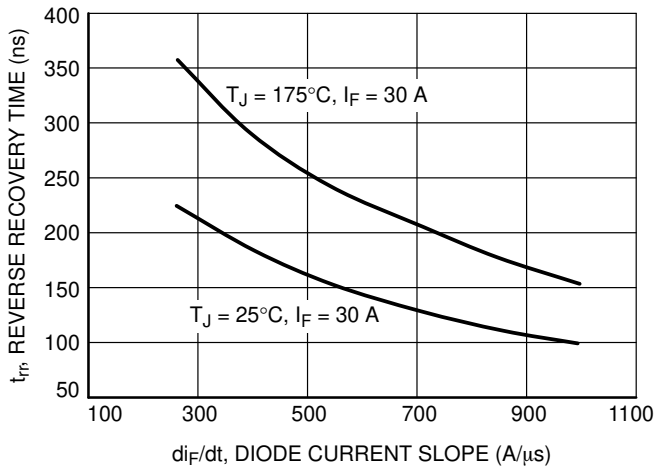


Figure 19. t_{rr} vs. di_F/dt
($V_R = 400\text{ V}$)

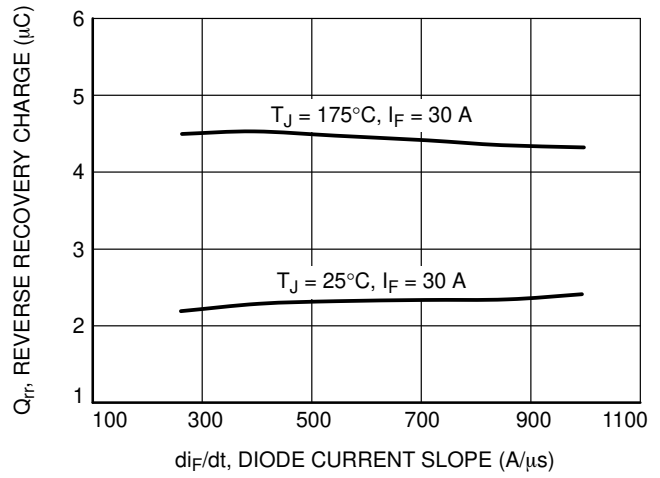


Figure 20. Q_{rr} vs. di_F/dt
($V_R = 400\text{ V}$)

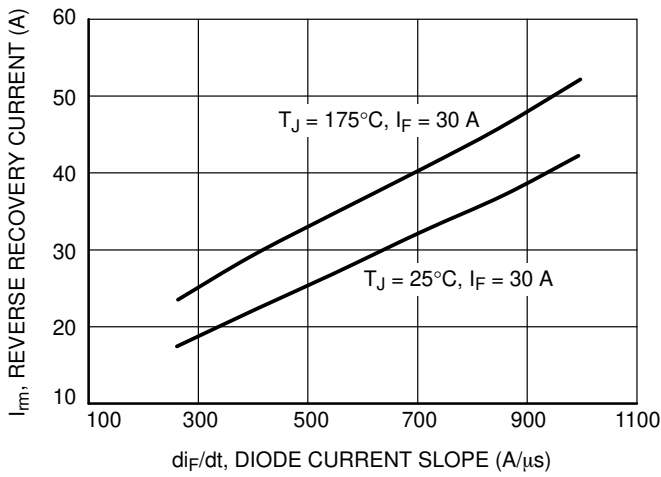


Figure 21. I_{rm} vs. di_F/dt
($V_R = 400\text{ V}$)

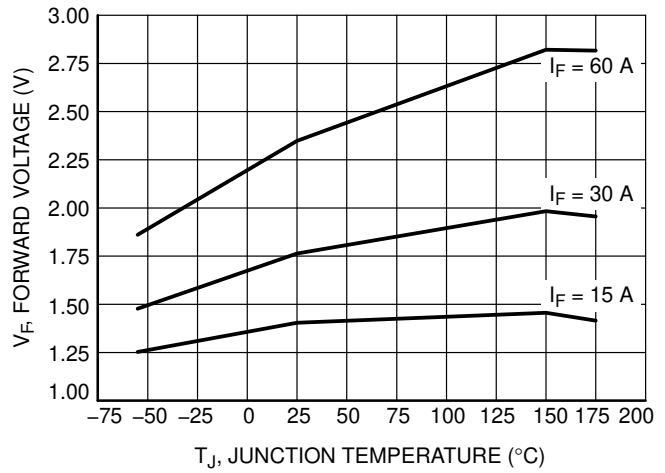


Figure 22. V_F vs. T_J

NGTB30N120FL2WG

TYPICAL CHARACTERISTICS

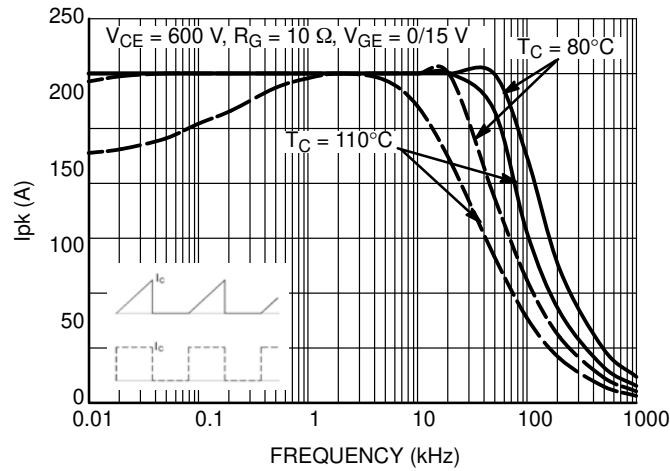


Figure 23. Collector Current vs. Switching Frequency

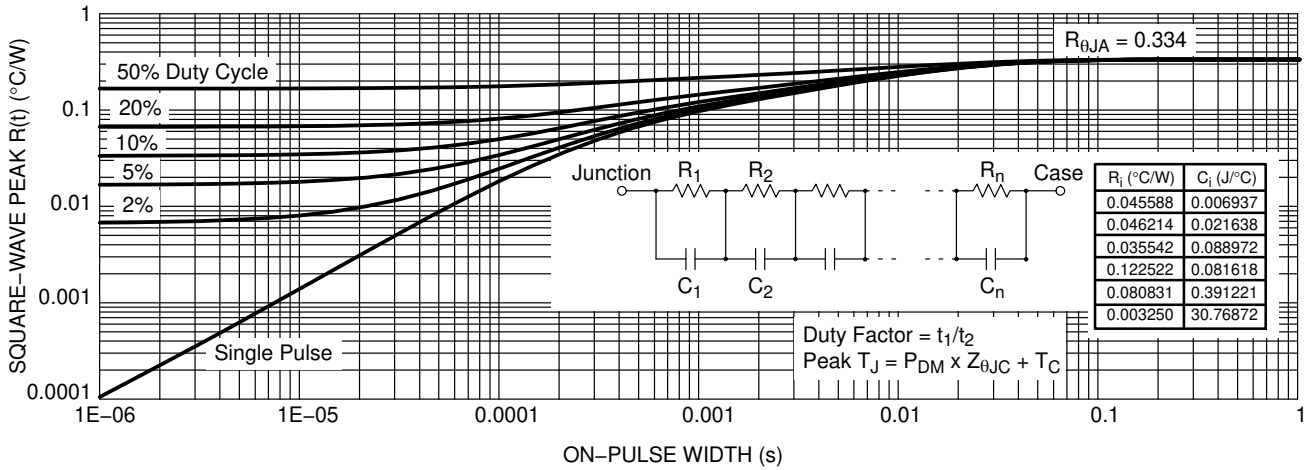


Figure 24. IGBT Transient Thermal Impedance

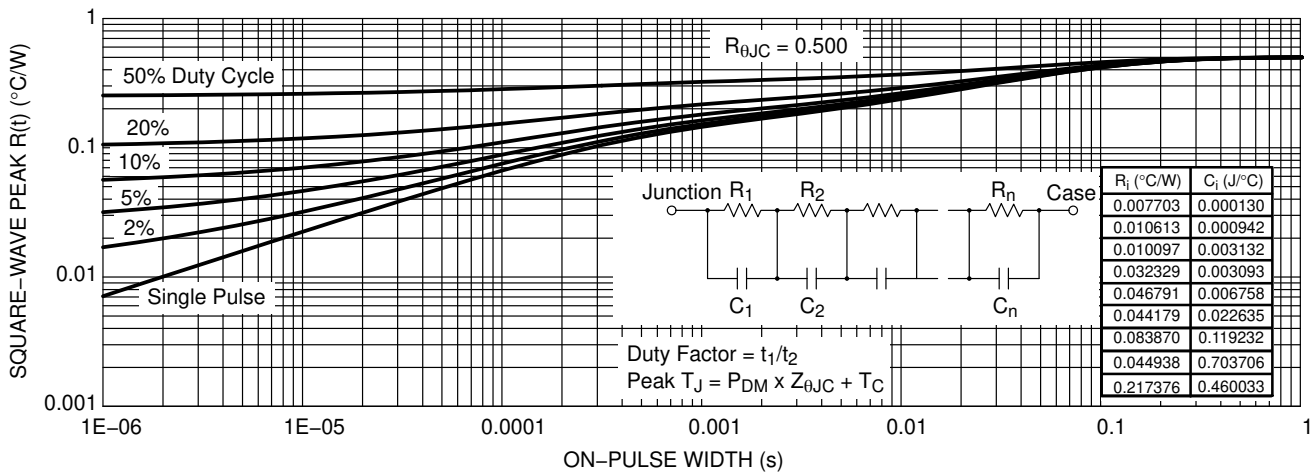


Figure 25. Diode Transient Thermal Impedance

